ECO SOLDER

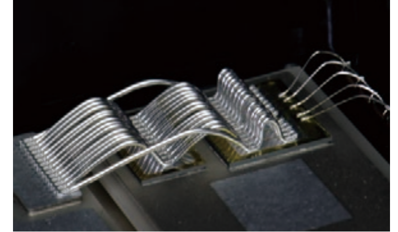
Solder Preform with Ni Balls

Expected Heat Dissipation by Uniform Solder Thickness

Features

- Achieved excellent heat dissipation with lower voids
- HQ type enables flux-free & no-clean die bonding
- Flux-coated type does not require flux application process

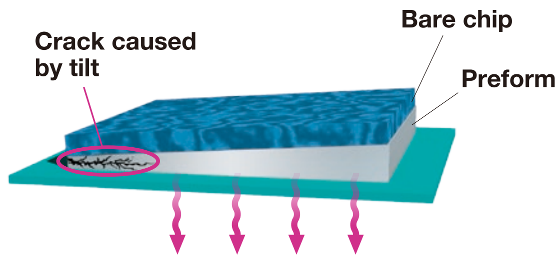
Die-bonding of power semiconductors

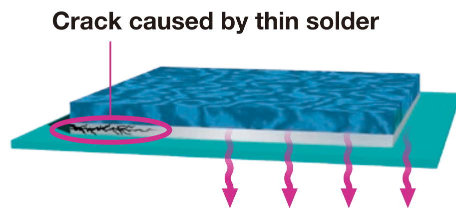


Revolutionary Products

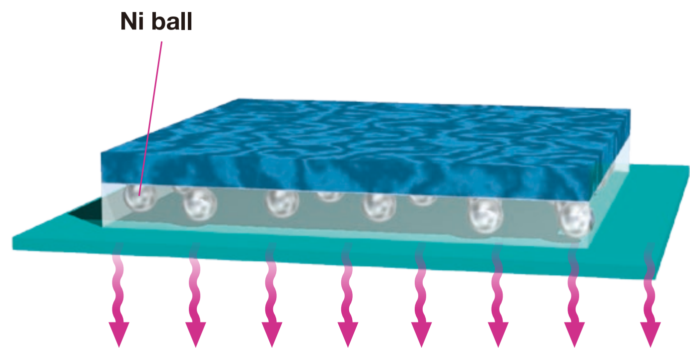
High heat dissipation

Air in cracks reduce thermal conductivity and lowers the heat dissipation effect





Excellent heat radiation



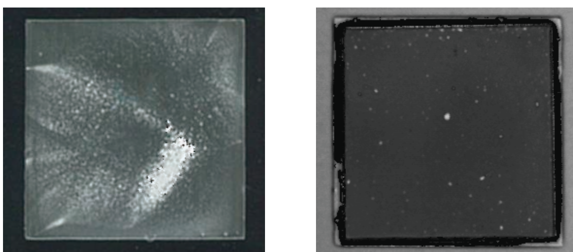
Unique ball inclusion technology exhibits excellent reaction and prevents voids

Ni balls provide stand-off heights between components, ensuring even solder thickness

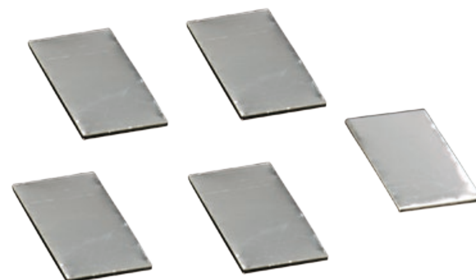
Available in different product types by application or purpose

HQ type does not require flux by special surface processing

HQ High-Quality Surface Condition



Flux-coated type applied flux on the surface



Flux can be selected by objective

SMIC